

**IN THE ABSTRACT OF THE DISCLOSURE**

Amend the abstract as follows:

The present invention provides a surface mount composite electronic component which can be made compact. The structure of the surface mount composite electronic component is one in which a circuit element (2) is formed on each of a set of opposing surfaces of an insulating substrate (1) composed of a hexahedron, with electrodes (3) that make up the circuit elements (2) also functioning as external terminals. For example, a pair of first electrodes (1a) disposed on both ends of a front surface of the insulating substrate (1) composed of a hexahedron, a pair of second electrodes (1b) disposed on a rear surface of the insulating substrate opposite the first electrodes, a first resistor (4a) disposed so as to contact both of the first pair of electrodes (1a), and a second resistor (4b) disposed so as to contact both of the second electrodes (1b).